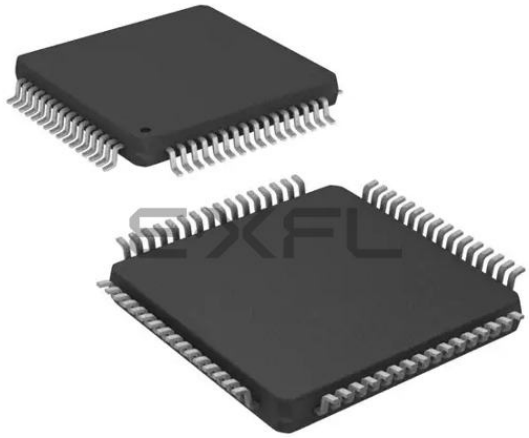
Microchip Technology - PIC32MX570F512HT-50I/PT Datasheet



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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	MIPS32® M4K™
Core Size	32-Bit Single-Core
Speed	50MHz
Connectivity	CANbus, I²C, IrDA, LINbus, PMP, SPI, UART/USART, USB OTG
Peripherals	Brown-out Detect/Reset, DMA, I²S, POR, PWM, WDT
Number of I/O	49
Program Memory Size	512KB (512K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	64K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 3.6V
Data Converters	A/D 28x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-TQFP
Supplier Device Package	64-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic32mx570f512ht-50i-pt

TABLE 3: PIN NAMES FOR 64-PIN USB DEVICES

64-PIN QFN(4) AND TQFP (TOP VIEW)

PIC32MX230F128H
PIC32MX530F128H
PIC32MX250F256H
PIC32MX550F256H
PIC32MX270F512H
PIC32MX570F512H

64 1

QFN(4)

64 1

TQFP

Pin #	Full Pin Name	Pin #	Full Pin Name
1	AN22/RPE5/PMD5/RE5	33	USBID/RPF3/RF3
2	AN23/PMD6/RE6	34	VBUS
3	AN27/PMD7/RE7	35	VUSB3V3
4	AN16/C1IND/RPG6/SCK2/PMA5/RG6	36	D-
5	AN17/C1INC/RPG7/PMA4/RG7	37	D+
6	AN18/C2IND/RPG8/PMA3/RG8	38	VDD
7	$\overline{\text{MCLR}}$	39	OSC1/CLKI/RC12
8	AN19/C2INC/RPG9/PMA2/RG9	40	OSC2/CLKO/RC15
9	VSS	41	VSS
10	VDD	42	RPD8/RTCC/RD8
11	AN5/C1INA/RPB5/VBUSON/RB5	43	RPD9/SDA1/RD9
12	AN4/C1INB/RB4	44	RPD10/SCL1/PMA15/RD10
13	PGED3/AN3/C2INA/RPB3/RB3	45	RPD11/PMA14/RD11
14	PGEC3/AN2/CTCMP/C2INB/RPB2/CTED13/RB2	46	RPD0/INT0/RD0
15	PGEC1/VREF-/AN1/RPB1/CTED12/RB1	47	SOSCI/RPC13/RC13
16	PGED1/VREF+/AN0/RPB0/PMA6/RB0	48	SOSCO/RPC14/T1CK/RC14
17	PGEC2/AN6/RPB6/RB6	49	AN24/RPD1/RD1
18	PGED2/AN7/RPB7/CTED3/RB7	50	AN25/RPD2/SCK1/RD2
19	AVDD	51	AN26/C3IND/RPD3/RD3
20	AVSS	52	RPD4/PMWR/RD4
21	AN8/RPB8/CTED10/RB8	53	RPD5/PMRD/RD5
22	AN9/RPB9/CTED4/PMA7/RB9	54	C3INC/RD6
23	TMS/CVREFOUT/AN10/RPB10/CTED11/PMA13/RB10	55	C3INB/RD7
24	TDO/AN11/PMA12/RB11	56	VCAP
25	VSS	57	VDD
26	VDD	58	C3INA/RPF0/RF0
27	TCK/AN12/PMA11/RB12	59	RPF1/RF1
28	TDI/AN13/PMA10/RB13	60	PMD0/RE0
29	AN14/RPB14/SCK3/CTED5/PMA1/RB14	61	PMD1/RE1
30	AN15/RPB15/OCFB/CTED6/PMA0/RB15	62	AN20/PMD2/RE2
31	RPF4/SDA2/PMA9/RF4	63	RPE3/CTPLS/PMD3/RE3
32	RPF5/SCL2/PMA8/RF5	64	AN21/PMD4/RE4

Note 1: The RPn pins can be used by remappable peripherals. See Table 1 for the available peripherals and **Section 11.3 "Peripheral Pin Select"** for restrictions.

2: Every I/O port pin (RBx-RGx) can be used as a change notification pin (CNBx-CNGx). See **Section 11.0 "I/O Ports"** for more information.

3: Shaded pins are 5V tolerant.

4: The metal plane at the bottom of the QFN device is not connected to any pins and is recommended to be connected to VSS externally.

TABLE 4: PIN NAMES FOR 100-PIN GENERAL PURPOSE DEVICES (CONTINUED)

100-PIN TQFP (TOP VIEW)

PIC32MX130F128L
PIC32MX150F256L
PIC32MX170F512L

100

1

Pin #	Full Pin Name	Pin #	Full Pin Name
71	RPD11/PMA14/RD11	86	VDD
72	RPD0/RD0	87	AN44/C3INA/RPF0/PMD11/RF0
73	SOSCI/RPC13/RC13	88	AN45/RPF1/PMD10/RF1
74	SOSCO/RPC14/T1CK/RC14	89	RPG1/PMD9/RG1
75	VSS	90	RPG0/PMD8/RG0
76	AN24/RPD1/RD1	91	RA6
77	AN25/RPD2/RD2	92	CTED8/RA7
78	AN26/C3IND/RPD3/RD3	93	AN46/PMD0/RE0
79	AN40/RPD12/PMD12/RD12	94	AN47/PMD1/RE1
80	AN41/PMD13/RD13	95	RG14
81	RPD4/PMWR/RD4	96	RG12
82	RPD5/PMRD/RD5	97	RG13
83	AN42/C3INC/PMD14/RD6	98	AN20/PMD2/RE2
84	AN43/C3INB/PMD15/RD7	99	RPE3/CTPLS/PMD3/RE3
85	VCAP	100	AN21/PMD4/RE4

Note 1: The RPn pins can be used by remappable peripherals. See Table 1 for the available peripherals and **Section 11.3 "Peripheral Pin Select"** for restrictions.

2: Every I/O port pin (RAx-RGx) can be used as a change notification pin (CNAx-CNGx). See **Section 11.0 "I/O Ports"** for more information.

3: Shaded pins are 5V tolerant.

1.0 DEVICE OVERVIEW

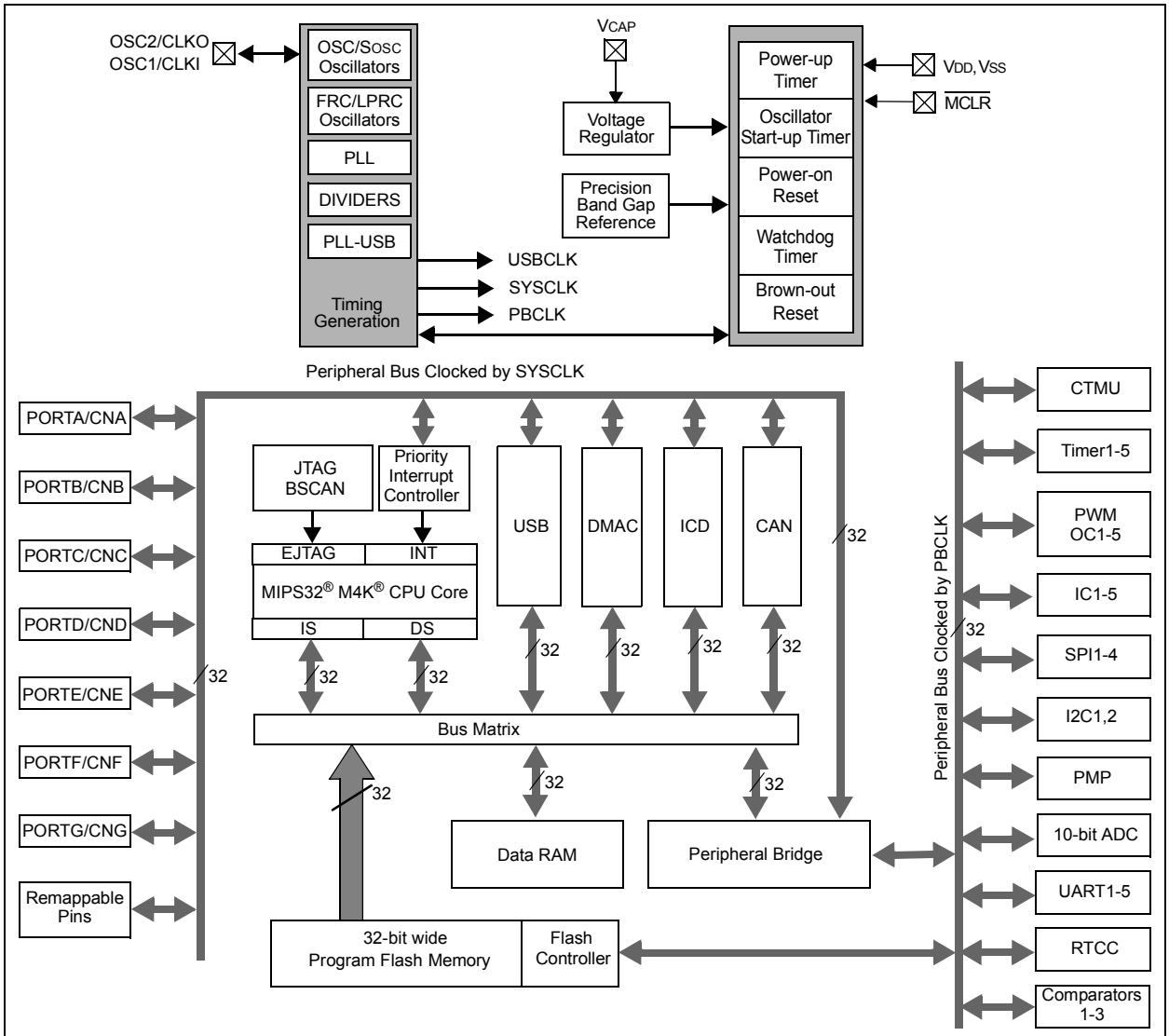
Note 1: This data sheet summarizes the features of the PIC32MX1XX/2XX/5XX 64/100-pin family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to the related section of the *"PIC32 Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com/PIC32).

This document contains device-specific information for PIC32MX1XX/2XX/5XX 64/100-pin devices.

Figure 1-1 illustrates a general block diagram of the core and peripheral modules in the PIC32MX1XX/2XX/5XX 64/100-pin family of devices.

Table 1-1 lists the functions of the various pins shown in the pinout diagrams.

FIGURE 1-1: PIC32MX1XX/2XX/5XX 64/100-PIN BLOCK DIAGRAM



Note: Not all features are available on all devices. Refer to **TABLE 1: "PIC32MX1XX/2XX/5XX 64/100-pin Controller Family Features"** for the list of features by device.

TABLE 1-1: PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number		Pin Type	Buffer Type	Description
	64-pin QFN/ TQFP	100-pin TQFP			
AN36	—	47	I	Analog	Analog input channels.
AN37	—	48	I	Analog	
AN38	—	52	I	Analog	
AN39	—	53	I	Analog	
AN40	—	79	I	Analog	
AN41	—	80	I	Analog	
AN42	—	83	I	Analog	
AN43	—	84	I	Analog	
AN44	—	87	I	Analog	
AN45	—	88	I	Analog	
AN46	—	93	I	Analog	
AN47	—	94	I	Analog	
CLKI	39	63	I	ST/CMOS	External clock source input. Always associated with OSC1 pin function.
CLKO	40	64	O	—	Oscillator crystal output. Connects to crystal or resonator in Crystal Oscillator mode. Optionally functions as CLKO in RC and EC modes. Always associated with the OSC2 pin function.
OSC1	39	63	I	ST/CMOS	Oscillator crystal input. ST buffer when configured in RC mode; CMOS otherwise.
OSC2	40	64	O	—	Oscillator crystal output. Connects to crystal or resonator in Crystal Oscillator mode. Optionally functions as CLKO in RC and EC modes.
SOSCI	47	73	I	ST/CMOS	32.768 kHz low-power oscillator crystal input; CMOS otherwise.
SOSCO	48	74	O	—	32.768 kHz low-power oscillator crystal output.
IC1	PPS	PPS	I	ST	Capture Input 1-5
IC2	PPS	PPS	I	ST	
IC3	PPS	PPS	I	ST	
IC4	PPS	PPS	I	ST	
IC5	PPS	PPS	I	ST	
OC1	PPS	PPS	O	ST	Output Compare Output 1
OC2	PPS	PPS	O	ST	Output Compare Output 2
OC3	PPS	PPS	O	ST	Output Compare Output 3
OC4	PPS	PPS	O	ST	Output Compare Output 4
OC5	PPS	PPS	O	ST	Output Compare Output 5
OCFA	PPS	PPS	I	ST	Output Compare Fault A Input
OCFB	30	44	I	ST	Output Compare Fault B Input

Legend: CMOS = CMOS compatible input or output Analog = Analog input I = Input O = Output
ST = Schmitt Trigger input with CMOS levels TTL = TTL input buffer P = Power

Note 1: This pin is only available on devices without a USB module.

2: This pin is only available on devices with a USB module.

3: This pin is not available on 64-pin devices with a USB module.

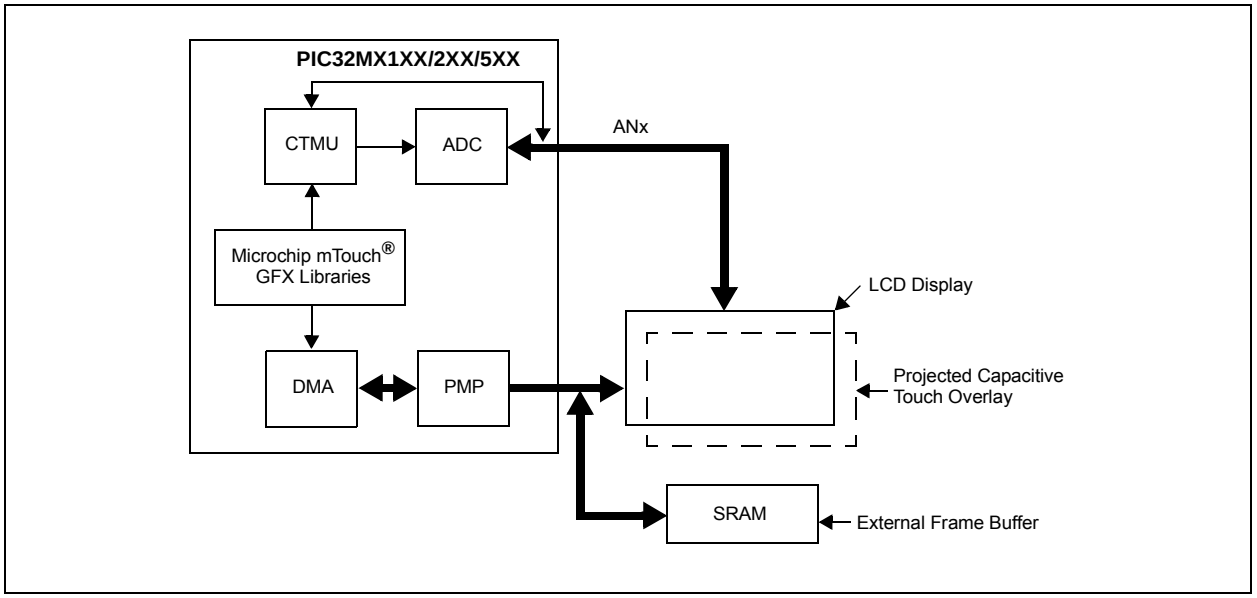
4: This pin is only available on 100-pin devices without a USB module.

2.8 Unused I/Os

Unused I/O pins should not be allowed to float as inputs. They can be configured as outputs and driven to a logic-low state.

Alternatively, inputs can be reserved by connecting the pin to VSS through a 1k to 10k resistor and configuring the pin as an input.

FIGURE 2-10: LOW-COST CONTROLLERLESS (LCC) GRAPHICS APPLICATION WITH PROJECTED CAPACITIVE TOUCH



4.2 Special Function Register Maps

TABLE 4-2: BUS MATRIX REGISTER MAP

Virtual Address (BF88_#)	Register Name	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
2000	BMXCON(1)	31:16	—	—	—	—	—	BMXCHEDMA	—	—	—	—	—	BMXERRIXI	BMXERRICD	BMXERRDMA	BMXERRDS	BMXERRIS	041F
		15:0	—	—	—	—	—	—	—	—	—	BMXWSDRM	—	—	—	BMXARB<2:0>			0047
2010	BMXDKPBA(1)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	BMXDKPBA<15:0>																0000
2020	BMXDUDBA(1)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	BMXDUDBA<15:0>																0000
2030	BMXDUPBA(1)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	BMXDUPBA<15:0>																0000
2040	BMXDRMSZ	31:16	BMXDRMSZ<31:0>																xxxx
		15:0																	xxxx
2050	BMXPUPBA(1)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	BMXPUPBA<19:16>				0000
		15:0	BMXPUPBA<15:0>																0000
2060	BMXPFMSZ	31:16	BMXPFMSZ<31:0>																xxxx
		15:0																	xxxx
2070	BMXBOOTSZ	31:16	BMXBOOTSZ<31:0>																0000
		15:0																	0000

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: This register has corresponding CLR, SET and INV registers at its virtual address, plus an offset of 0x4, 0x8 and 0xC, respectively. See **Section 11.2 "CLR, SET, and INV Registers"** for more information.

REGISTER 4-5: BMXDRMSZ: DATA RAM SIZE REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	R	R	R	R	R	R	R	R
	BMXDRMSZ<31:24>							
23:16	R	R	R	R	R	R	R	R
	BMXDRMSZ<23:16>							
15:8	R	R	R	R	R	R	R	R
	BMXDRMSZ<15:8>							
7:0	R	R	R	R	R	R	R	R
	BMXDRMSZ<7:0>							

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-0 **BMXDRMSZ<31:0>:** Data RAM Memory (DRM) Size bits
Static value that indicates the size of the Data RAM in bytes:
0x00002000 = Device has 8 KB RAM
0x00004000 = Device has 16 KB RAM
0x00008000 = Device has 32 KB RAM
0x00010000 = Device has 64 KB RAM

REGISTER 4-6: BMXPUPBA: PROGRAM FLASH (PFM) USER PROGRAM BASE ADDRESS REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0
	—	—	—	—	BMXPUPBA<19:16>			
15:8	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R-0	R-0	R-0
	BMXPUPBA<15:8>							
7:0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0
	BMXPUPBA<7:0>							

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-20 **Unimplemented:** Read as '0'

bit 19-11 **BMXPUPBA<19:11>:** Program Flash (PFM) User Program Base Address bits

bit 10-0 **BMXPUPBA<10:0>:** Read-Only bits
Value is always '0', which forces 2 KB increments

Note 1: At Reset, the value in this register is forced to zero, which causes all of the RAM to be allocated to Kernel mode data usage.
2: The value in this register must be less than or equal to BMXPFMSZ.

10.0 USB ON-THE-GO (OTG)

Note: This data sheet summarizes the features of the PIC32MX1XX/2XX/5XX 64/100-pin family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 27. "USB On-The-Go (OTG)"** (DS60001126) in the *"PIC32 Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com/PIC32).

The Universal Serial Bus (USB) module contains analog and digital components to provide a USB 2.0 full-speed and low-speed embedded host, full-speed device or OTG implementation with a minimum of external components. This module in Host mode is intended for use as an embedded host and therefore does not implement a UHCI or OHCI controller.

The USB module consists of the clock generator, the USB voltage comparators, the transceiver, the Serial Interface Engine (SIE), a dedicated USB DMA controller, pull-up and pull-down resistors, and the register interface. A block diagram of the PIC32 USB OTG module is presented in Figure 10-1.

The clock generator provides the 48 MHz clock required for USB full-speed and low-speed communication. The voltage comparators monitor the voltage on the VBUS pin to determine the state of the bus. The transceiver provides the analog translation between the USB bus and the digital logic. The SIE is a state machine that transfers data to and from the endpoint buffers and generates the hardware protocol for data transfers. The USB DMA controller transfers data between the data buffers in RAM and the SIE. The integrated pull-up and pull-down resistors eliminate the need for external signaling components. The register interface allows the CPU to configure and communicate with the module.

The PIC32 USB module includes the following features:

- USB Full-speed support for host and device
- Low-speed host support
- USB OTG support
- Integrated signaling resistors
- Integrated analog comparators for VBUS monitoring
- Integrated USB transceiver
- Transaction handshaking performed by hardware
- Endpoint buffering anywhere in system RAM
- Integrated DMA to access system RAM and Flash

Note: The implementation and use of the USB specifications, and other third party specifications or technologies, may require licensing; including, but not limited to, USB Implementers Forum, Inc. (also referred to as USB-IF). The user is fully responsible for investigating and satisfying any applicable licensing obligations.

11.3 Peripheral Pin Select

A major challenge in general purpose devices is providing the largest possible set of peripheral features while minimizing the conflict of features on I/O pins. The challenge is even greater on low pin count devices. In an application where more than one peripheral needs to be assigned to a single pin, inconvenient workarounds in application code or a complete redesign may be the only options.

Peripheral pin select configuration provides an alternative to these choices by enabling peripheral set selection and their placement on a wide range of I/O pins. By increasing the pinout options available on a particular device, users can better tailor the device to their entire application, rather than trimming the application to fit the device.

The peripheral pin select configuration feature operates over a fixed subset of digital I/O pins. Users may independently map the input and/or output of most digital peripherals to these I/O pins. Peripheral pin select is performed in software and generally does not require the device to be reprogrammed. Hardware safeguards are included that prevent accidental or spurious changes to the peripheral mapping once it has been established.

11.3.1 AVAILABLE PINS

The number of available pins is dependent on the particular device and its pin count. Pins that support the peripheral pin select feature include the designation "RPn" in their full pin designation, where "RP" designates a remappable peripheral and "n" is the remappable port number.

11.3.2 AVAILABLE PERIPHERALS

The peripherals managed by the peripheral pin select are all digital-only peripherals. These include general serial communications (UART and SPI), general purpose timer clock inputs, timer-related peripherals (input capture and output compare) and interrupt-on-change inputs.

In comparison, some digital-only peripheral modules are never included in the peripheral pin select feature. This is because the peripheral's function requires special I/O circuitry on a specific port and cannot be easily connected to multiple pins. These modules include I^2C among others. A similar requirement excludes all modules with analog inputs, such as the Analog-to-Digital Converter (ADC).

A key difference between remappable and non-remappable peripherals is that remappable peripherals are not associated with a default I/O pin. The peripheral must always be assigned to a specific I/O pin before it can be used. In contrast, non-remappable peripherals are always available on a default pin, assuming that the peripheral is active and not conflicting with another peripheral.

When a remappable peripheral is active on a given I/O pin, it takes priority over all other digital I/O and digital communication peripherals associated with the pin. Priority is given regardless of the type of peripheral that is mapped. Remappable peripherals never take priority over any analog functions associated with the pin.

11.3.3 CONTROLLING PERIPHERAL PIN SELECT

Peripheral pin select features are controlled through two sets of SFRs: one to map peripheral inputs, and one to map outputs. Because they are separately controlled, a particular peripheral's input and output (if the peripheral has both) can be placed on any selectable function pin without constraint.

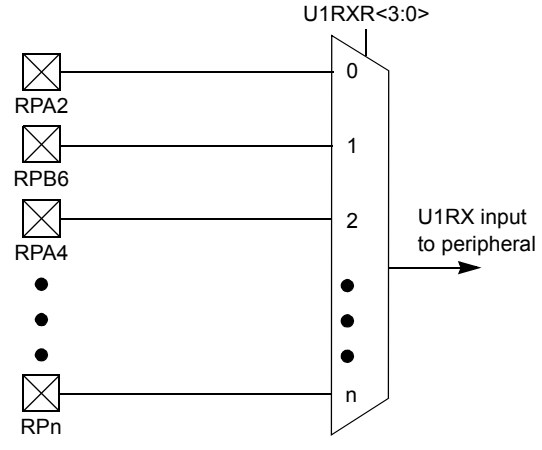
The association of a peripheral to a peripheral-selectable pin is handled in two different ways, depending on whether an input or output is being mapped.

11.3.4 INPUT MAPPING

The inputs of the peripheral pin select options are mapped on the basis of the peripheral. That is, a control register associated with a peripheral dictates the pin it will be mapped to. The [*pin name*]R registers, where [*pin name*] refers to the peripheral pins listed in Table 11-1, are used to configure peripheral input mapping (see Register 11-1). Each register contains sets of 4 bit fields. Programming these bit fields with an appropriate value maps the RPn pin with the corresponding value to that peripheral. For any given device, the valid range of values for any bit field is shown in Table 11-1.

For example, Figure 11-2 illustrates the remappable pin selection for the U1RX input.

FIGURE 11-2: REMAPPABLE INPUT EXAMPLE FOR U1RX



Note: For input only, peripheral pin select functionality does not have priority over TRISx settings. Therefore, when configuring RPn pin for input, the corresponding bit in the TRISx register must also be configured for input (set to '1').

REGISTER 12-1: T1CON: TYPE A TIMER CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R/W-0	U-0	R/W-0	R/W-0	R-0	U-0	U-0	U-0
	ON(1)	—	SIDL	TWDIS	TWIP	—	—	—
7:0	R/W-0	U-0	R/W-0	R/W-0	U-0	R/W-0	R/W-0	U-0
	TGATE	—	TCKPS<1:0>		—	TSYNC	TCS	—

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-16 **Unimplemented:** Read as '0'

bit 15 **ON:** Timer On bit(1)
- 1 = Timer is enabled
- 0 = Timer is disabled

bit 14 **Unimplemented:** Read as '0'

bit 13 **SIDL:** Stop in Idle Mode bit
- 1 = Discontinue operation when device enters Idle mode
- 0 = Continue operation even in Idle mode

bit 12 **TWDIS:** Asynchronous Timer Write Disable bit
- 1 = Writes to TMR1 are ignored until pending write operation completes
- 0 = Back-to-back writes are enabled (Legacy Asynchronous Timer functionality)

bit 11 **TWIP:** Asynchronous Timer Write in Progress bit

In Asynchronous Timer mode:
- 1 = Asynchronous write to TMR1 register in progress
- 0 = Asynchronous write to TMR1 register complete

In Synchronous Timer mode:
This bit is read as '0'.

bit 10-8 **Unimplemented:** Read as '0'

bit 7 **TGATE:** Timer Gated Time Accumulation Enable bit

When TCS = 1:
This bit is ignored.

When TCS = 0:
- 1 = Gated time accumulation is enabled
- 0 = Gated time accumulation is disabled

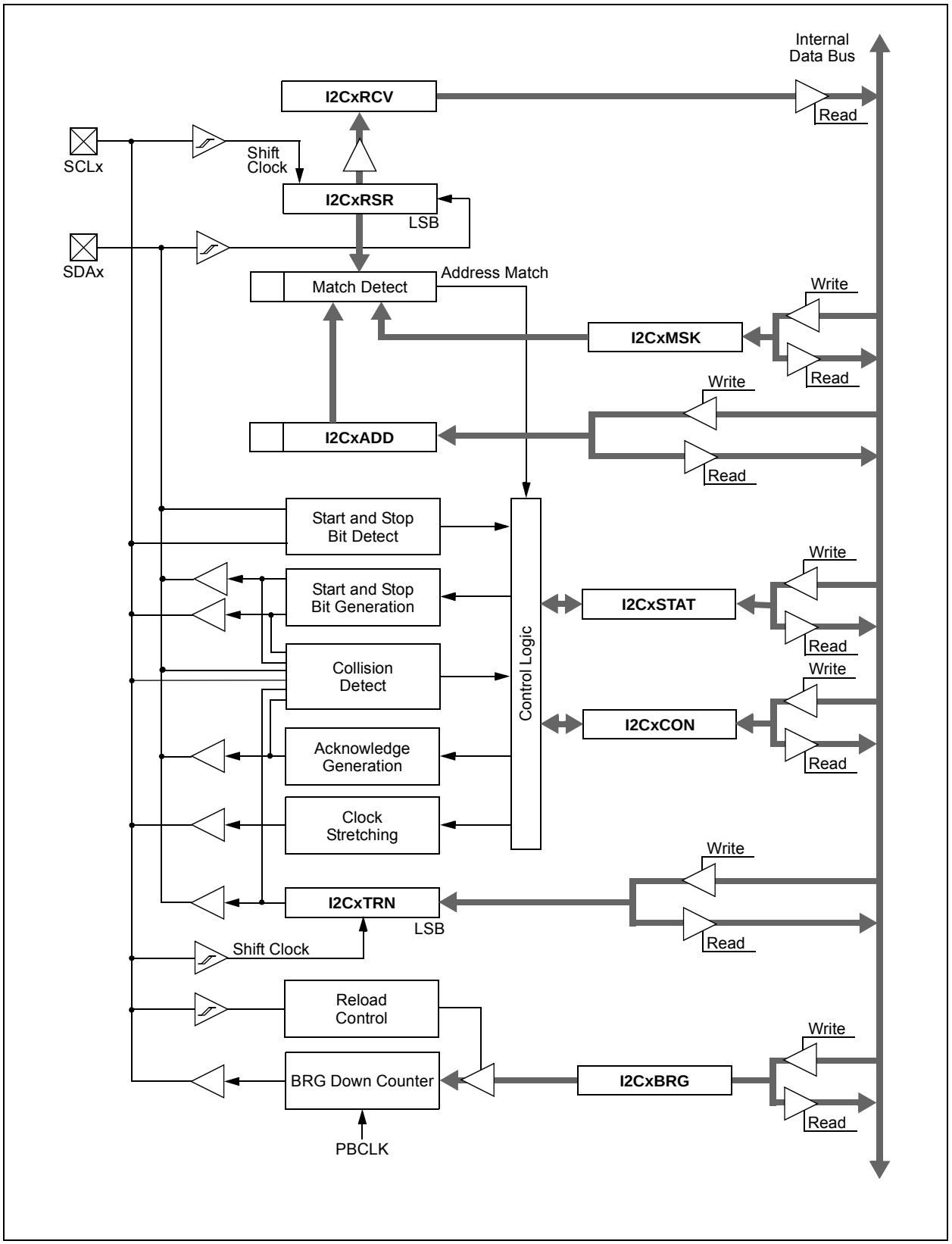
bit 6 **Unimplemented:** Read as '0'

bit 5-4 **TCKPS<1:0>:** Timer Input Clock Prescale Select bits
- 11 = 1:256 prescale value
- 10 = 1:64 prescale value
- 01 = 1:8 prescale value
- 00 = 1:1 prescale value

bit 3 **Unimplemented:** Read as '0'

Note 1: When using 1:1 PBCLK divisor, the user's software should not read/write the peripheral SFRs in the SYSCLK cycle immediately following the instruction that clears the module's ON bit.

FIGURE 18-1: I²C BLOCK DIAGRAM



REGISTER 23-2: C1CFG: CAN BAUD RATE CONFIGURATION REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	R/W-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0
	—	WAKFIL	—	—	—	SEG2PH<2:0>(1,4)		
15:8	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	SEG2PHTS(1)	SAM(2)	SEG1PH<2:0>			PRSEG<2:0>		
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	SJW<1:0>(3)		BRP<5:0>					

Legend:	HC = Hardware Clear	S = Settable bit	
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-23 **Unimplemented:** Read as '0'

bit 22 **WAKFIL:** CAN Bus Line Filter Enable bit
1 = Use CAN bus line filter for wake-up
0 = CAN bus line filter is not used for wake-up

bit 21-19 **Unimplemented:** Read as '0'

bit 18-16 **SEG2PH<2:0>:** Phase Buffer Segment 2 bits(1,4)
111 = Length is 8 x TQ
•
•
•
000 = Length is 1 x TQ

bit 15 **SEG2PHTS:** Phase Segment 2 Time Select bit(1)
1 = Freely programmable
0 = Maximum of SEG1PH or Information Processing Time, whichever is greater

bit 14 **SAM:** Sample of the CAN Bus Line bit(2)
1 = Bus line is sampled three times at the sample point
0 = Bus line is sampled once at the sample point

bit 13-11 **SEG1PH<2:0>:** Phase Buffer Segment 1 bits(4)
111 = Length is 8 x TQ
•
•
•
000 = Length is 1 x TQ

Note 1: SEG2PH ≤ SEG1PH. If SEG2PHTS is clear, SEG2PH will be set automatically.
2: 3 Time bit sampling is not allowed for BRP < 2.
3: SJW ≤ SEG2PH.
4: The Time Quanta per bit must be greater than 7 (that is, TQBIT > 7).

Note: This register can only be modified when the CAN module is in Configuration mode (OPMOD<2:0> (C1CON<23:21>) = 100).

REGISTER 23-11: C1FLTCON1: CAN FILTER CONTROL REGISTER 1 (CONTINUED)

bit 20-16 **FSEL6<4:0>:** FIFO Selection bits
11111 = Reserved
.
.
.
10000 = Reserved
01111 = Message matching filter is stored in FIFO buffer 15
.
.
.
00000 = Message matching filter is stored in FIFO buffer 0

bit 15 **FLTEN5:** Filter 17 Enable bit
1 = Filter is enabled
0 = Filter is disabled

bit 14-13 **MSEL5<1:0>:** Filter 5 Mask Select bits
11 = Acceptance Mask 3 selected
10 = Acceptance Mask 2 selected
01 = Acceptance Mask 1 selected
00 = Acceptance Mask 0 selected

bit 12-8 **FSEL5<4:0>:** FIFO Selection bits
11111 = Reserved
.
.
.
10000 = Reserved
01111 = Message matching filter is stored in FIFO buffer 15
.
.
.
00000 = Message matching filter is stored in FIFO buffer 0

bit 7 **FLTEN4:** Filter 4 Enable bit
1 = Filter is enabled
0 = Filter is disabled

bit 6-5 **MSEL4<1:0>:** Filter 4 Mask Select bits
11 = Acceptance Mask 3 selected
10 = Acceptance Mask 2 selected
01 = Acceptance Mask 1 selected
00 = Acceptance Mask 0 selected

bit 4-0 **FSEL4<4:0>:** FIFO Selection bits
11111 = Reserved
.
.
.
10000 = Reserved
01111 = Message matching filter is stored in FIFO buffer 15
.
.
.
00000 = Message matching filter is stored in FIFO buffer 0

Note: The bits in this register can only be modified if the corresponding filter enable (FLTENn) bit is '0'.

REGISTER 26-1: CTMUCON: CTMU CONTROL REGISTER (CONTINUED)

bit 24 **EDG1STAT:** Edge 1 Status bit
Indicates the status of Edge 1 and can be written to control edge source
1 = Edge 1 has occurred
0 = Edge 1 has not occurred

bit 23 **EDG2MOD:** Edge 2 Edge Sampling Select bit
1 = Input is edge-sensitive
0 = Input is level-sensitive

bit 22 **EDG2POL:** Edge 2 Polarity Select bit
1 = Edge 2 programmed for a positive edge response
0 = Edge 2 programmed for a negative edge response

bit 21-18 **EDG2SEL<3:0>:** Edge 2 Source Select bits
1111 = IC4 Capture Event is selected
1110 = C2OUT pin is selected
1101 = C1OUT pin is selected
1100 = PBCLK clock is selected
1011 = IC3 Capture Event is selected
1010 = IC2 Capture Event is selected
1001 = IC1 Capture Event is selected
1000 = CTED13 pin is selected
0111 = CTED12 pin is selected
0110 = CTED11 pin is selected
0101 = CTED10 pin is selected
0100 = CTED9 pin is selected
0011 = CTED1 pin is selected
0010 = CTED2 pin is selected
0001 = OC1 Compare Event is selected
0000 = Timer1 Event is selected

bit 17-16 **Unimplemented:** Read as '0'

bit 15 **ON:** ON Enable bit
1 = Module is enabled
0 = Module is disabled

bit 14 **Unimplemented:** Read as '0'

bit 13 **CTMUSIDL:** Stop in Idle Mode bit
1 = Discontinue module operation when device enters Idle mode
0 = Continue module operation in Idle mode

bit 12 **TGEN:** Time Generation Enable bit**(1)**
1 = Enables edge delay generation
0 = Disables edge delay generation

bit 11 **EDGEN:** Edge Enable bit
1 = Edges are not blocked
0 = Edges are blocked

Note 1: When this bit is set for Pulse Delay Generation, the EDG2SEL<3:0> bits must be set to '1110' to select C2OUT.

2: The ADC module Sample and Hold capacitor is not automatically discharged between sample/conversion cycles. Software using the ADC as part of a capacitive measurement, must discharge the ADC capacitor before conducting the measurement. The IDISSEN bit, when set to '1', performs this function. The ADC module must be sampling while the IDISSEN bit is active to connect the discharge sink to the capacitor array.

3: Refer to the CTMU Current Source Specifications (Table 31-41) in **Section 31.0 "40 MHz Electrical Characteristics"** for current values.

4: This bit setting is not available for the CTMU temperature diode.

29.0 INSTRUCTION SET

The PIC32MX1XX/2XX/5XX 64/100-pin family instruction set complies with the MIPS32® Release 2 instruction set architecture. The PIC32 device family does not support the following features:

- Core extend instructions
- Coprocessor 1 instructions
- Coprocessor 2 instructions

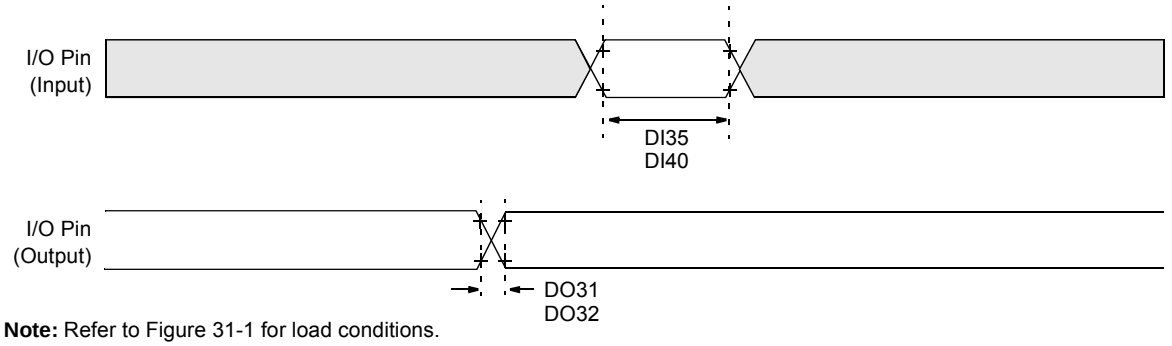
Note: Refer to *"MIPS32® Architecture for Programmers Volume II: The MIPS32® Instruction Set"* at www.imgtec.com for more information.

TABLE 31-9: DC CHARACTERISTICS: I/O PIN OUTPUT SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param.	**Symbol**	**Characteristic**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
DO10	VOL	**Output Low Voltage** I/O Pins: 4x Sink Driver Pins - All I/O output pins not defined as 8x Sink Driver pins	—	—	0.4	V	IOL ≤ 9 mA, VDD = 3.3V
		Output Low Voltage I/O Pins: 8x Sink Driver Pins - RB14, RC15, RD2, RD10, RD15, RF6, RF13, RG6	—	—	0.4	V	IOL ≤ 15 mA, VDD = 3.3V
DO20	VOH	**Output High Voltage** I/O Pins: 4x Source Driver Pins - All I/O output pins not defined as 8x Source Driver pins	2.4	—	—	V	IOH ≥ -10 mA, VDD = 3.3V
		Output High Voltage I/O Pins: 8x Source Driver Pins - RB14, RC15, RD2, RD10, RD15, RF6, RF13, RG6	2.4	—	—	V	IOH ≥ -15 mA, VDD = 3.3V
DO20A	VOH1	**Output High Voltage** I/O Pins: 4x Source Driver Pins - All I/O output pins not defined as 8x Sink Driver pins	1.5(1)	—	—	V	IOH ≥ -14 mA, VDD = 3.3V
			2.0(1)	—	—		IOH ≥ -12 mA, VDD = 3.3V
			3.0(1)	—	—		IOH ≥ -7 mA, VDD = 3.3V
		Output High Voltage I/O Pins: 8x Source Driver Pins - RB14, RC15, RD2, RD10, RD15, RF6, RF13, RG6	1.5(1)	—	—	V	IOH ≥ -22 mA, VDD = 3.3V
			2.0(1)	—	—		IOH ≥ -18 mA, VDD = 3.3V
			3.0(1)	—	—		IOH ≥ -10 mA, VDD = 3.3V

Note 1: Parameters are characterized, but not tested.

FIGURE 31-3: I/O TIMING CHARACTERISTICS



Note: Refer to Figure 31-1 for load conditions.

TABLE 31-21: I/O TIMING REQUIREMENTS

AC CHARACTERISTICS			**Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics(2)**	**Min.**	**Typical(1)**	**Max.**	**Units**	**Conditions**
DO31	TIOR	Port Output Rise Time	—	5	15	ns	VDD < 2.5V
			—	5	10	ns	VDD > 2.5V
DO32	TIOF	Port Output Fall Time	—	5	15	ns	VDD < 2.5V
			—	5	10	ns	VDD > 2.5V
DI35	TINP	INTx Pin High or Low Time	10	—	—	ns	—
DI40	TRBP	CNx High or Low Time (input)	2	—	—	TSYSCLK	—

Note 1: Data in "Typical" column is at 3.3V, 25°C unless otherwise stated.

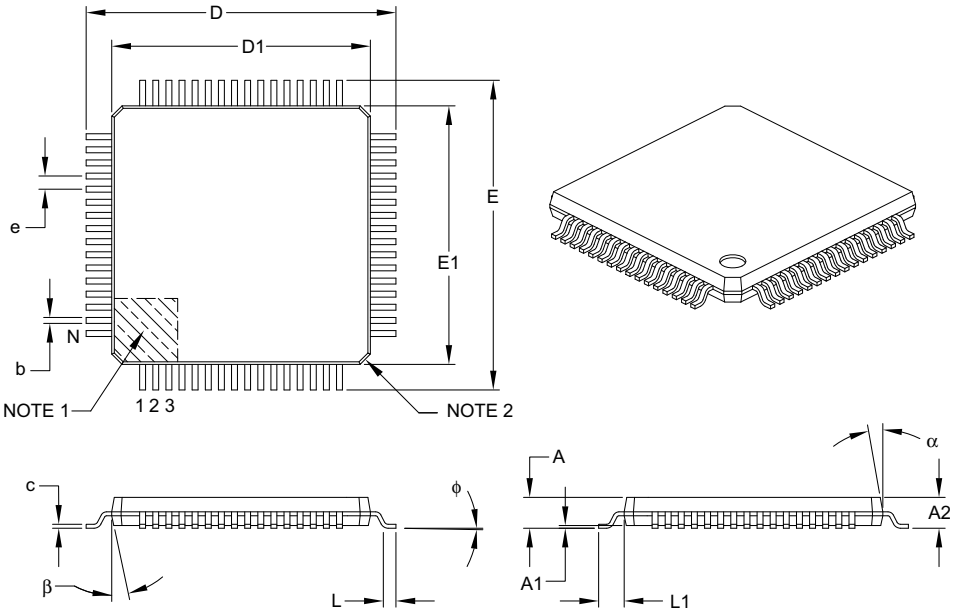
2: This parameter is characterized, but not tested in manufacturing.

34.2 Package Details

The following sections give the technical details of the packages.

64-Lead Plastic Thin Quad Flatpack (PT) – 10x10x1 mm Body, 2.00 mm [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Leads	N		64	
Lead Pitch	e		0.50 BSC	
Overall Height	A	–	–	1.20
Molded Package Thickness	A2	0.95	1.00	1.05
Standoff	A1	0.05	–	0.15
Foot Length	L	0.45	0.60	0.75
Footprint	L1		1.00 REF	
Foot Angle	ϕ	0°	3.5°	7°
Overall Width	E		12.00 BSC	
Overall Length	D		12.00 BSC	
Molded Package Width	E1		10.00 BSC	
Molded Package Length	D1		10.00 BSC	
Lead Thickness	c	0.09	–	0.20
Lead Width	b	0.17	0.22	0.27
Mold Draft Angle Top	α	11°	12°	13°
Mold Draft Angle Bottom	β	11°	12°	13°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Chamfers at corners are optional; size may vary.
3. Dimensions D1 and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.25 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-085B

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